

# **Technical** Data Sheet

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# Chemask® LF Lead-Free Solder Masking Agent

## Product# CLF8, CLF1

#### **Product Description**

Chemask LF Lead-Free Solder Masking Agent is a temporary, fast curing, peelable solder masking agent formulated for use in high temperature lead-free applications. It is a temperature resistant coating that protects component-free areas of the PCB during wave soldering. Chemask Lead-Free can be introduced into the preheat oven within 4 minutes of application without adverse effects. Use to protect pins, posts, contacts and edge connections during conformal coating processes.

- Stable to 550°F (288°C)
- Can be used in lead-free or Tin/Lead applications
- · Compatible with rosin, no clean, and water soluble fluxes
- · Unaffected by cleaning solvents
- Leaves no residue non-contaminating
- Ready for wave solder in 4 minutes
- Dries tack free in 15 minutes
- RoHS compliant

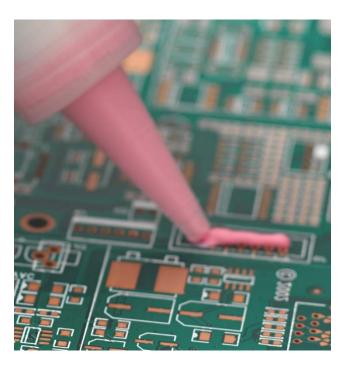
### **Typical Applications**

Chemask LF Lead-Free Solder Masking Agent protects:

- · ComponentfFree areas for soldering
- Components and sockets
- · Pin connectors during soldering

 Temperature sensitive components during wave soldering





# **Typical Product Data and Physical Properties**

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Base Material	Natural latex rubber	
Color	Pink	
Solvent Stability	Stable in all hydrocarbon,	
(cured mask)	hydrofluorocarbon, chlorinated,	
	and halogenated solvents	
Flux Compatibility	All types	
Temperature Stability	550°F/ 288°C	
Tack-Free Drying Time	15 min.	
(10 mils @ 77°F/25°C)		
Cure Time	30 min.	
(10 mils @ 77°F/25°C)		
Viscosity (@ 77°F)	190,000 cps	
$(\pm  500  cps)$		
Viscosity Adjusted With	Deionized water	
Solids Content	~ 80%	
Flash Point	Nonflammable	
Weight/Gallon	7.2 lbs.	
Shelflife	2 years	
RoHS Compliant		

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### Compatibility

Chemask LF Lead-Free Solder Masking Agent is generally compatible with most materials used in printed circuit board fabrication. As with any solder masking agent, compatibility with substrate must be determined on a non-critical area prior to use. Test compatibility on bare copper.

## **Application Method**

Squeeze Bottle/Syringe	Yes	
Spatula	Yes	
Screening	No	
Automatic Dispensing	Yes	
Removal/Clean-up	By Hand	

#### **Usage Instructions**

#### For industrial use only. Read SDS carefully prior to use.

Chemask LF Lead-Free Solder Masking Agent is engineered for all electronic manufacturing applications. When applying by hand using squeeze bottle, syringe or spatula, insure that all areas of the pretinned hole are evenly covered on the side to be soldered. Automatic dispensing equipment may also be used as appropriate.

**REMOVAL:** After allowing the mask to become fully cured, peelable solder mask can be removed by hand or by the use of tweezers. Depending on ambient conditions, peelable mask may remain on assemblies for extended periods of time prior to component insertion.

#### Availability

 CLF8
 8 fl. oz. / 236 mL Liquid

 CLF1
 1 gal. / 3.7 L Liquid

#### **Technical and Application Assistance**

Chemtronics provides a technical hotline to answer your technical and application related questions.

The toll free number is: 1-800-TECH-401.

#### Note:

This information is believed to be accurate. It is intended for professional end users having the skills to evaluate and use the data properly. CHEMTRONICS does not guarantee the accuracy of the data and assumes no liability in connection with damages incurred while using it.

